

DECLARATION FOR PATENT APPLICATION

USP031016P
(03S1800P1)

As a below named inventor, I declare :
that I verily believe myself to be the original, first and sole (if only one individual inventor is listed below) or an original, first and joint inventor (if more than one individual inventor is listed below) of the invention in

SINGLE-SUBSTRATE HEAT-PROCESSING APPARATUS FOR SEMICONDUCTOR PROCESSING SYSTEM

the specification of which is attached hereto unless the following box is checked.

☒ was filed on May 26, 2004 as United States Application or PCT International Application No. PCT/JP2004/007572, and was amended on _____ (if applicable).

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above. I acknowledge the duty to disclose information of which is material to patentability as defined in 37 CFR 1.56.

I hereby claim foreign priority benefits under 35 U.S.C. 119(a)-(d) or 365(b) of any foreign application(s) for patent or inventor's certificate, or 35 U.S.C. 365(a) of any PCT International application which designated at least one country other than the United States, listed below and have also identified below any foreign application for patent or inventor's certificate, or PCT International application having a filing date before that of the application on which priority is claimed:

<u>Country</u>	<u>Category</u>	<u>Application Number</u>	<u>Filing Date</u>	<u>Priority Claim</u>
Japan	Patent	2003-172633	June 17, 2003	Yes

I hereby appoint as my attorneys, with full power of substitution and revocation, to prosecute this application and transact all business in the Patent and Trademark Office connected therewith: the practitioners at:

Customer Number : 22850

of Oblon, Spivak, McClelland, Maier & Neustadt, P.C.. Please address all correspondence and telephone communications to the address and telephone number for this Customer Number.

I declare further that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

DECLARATION FOR PATENT APPLICATION

USP031016P
(03S1800P1)

I declare further that my citizenship, residence and mailing address are as stated below next to my name:

[1st Inventor]

Residence Address: Tokyo, Japan JPX

Mailing Address: c/o Intellectual Property Department, TOKYO ELECTRON LIMITED, 3-6, Akasaka
5-chome, Minato-ku, Tokyo 107-8481 Japan

Citizenship: Japan

Kenichi Yamaga

Kenichi Yamaga

Date:

January 28, 2005

[2nd Inventor]

Residence Address: Tokyo, Japan JPX

Mailing Address: c/o Intellectual Property Department, TOKYO ELECTRON LIMITED, 3-6, Akasaka
5-chome, Minato-ku, Tokyo 107-8481 Japan

Citizenship: Japan

Ken Nakao

Ken Nakao

Date:

January 28, 2005

[3rd Inventor]

Residence Address:

Mailing Address:

Citizenship:

Date:

[4th Inventor]

Residence Address:

Mailing Address:

Citizenship:

Date:

[5th Inventor]

Residence Address:

Mailing Address:

Citizenship:

Date: